

# ACKNOWLEDGEMENT RECEIPT

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## Title of Invention

Elimination of RDL Using Tape Base Flip Chip on Flex for Die Stacking

Submission Type : Information Disclosure Statement

Application Number:

10/050507



EFS ID:

100582

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Attorney Docket Number:

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File Listing:

Doc. Name	File Name	Size (Bytes)	Date Produced (yyyymmdd)
us-ids	MTI-31607c-usidst.xml	1490	2006-01-03
us-ids	us-ids.dtd	7763	2006-01-03
us-ids	us-ids.xml	12026	2006-01-03
package-data	MTI-31607c-pkda.xml	1732	2006-01-03
package-data	package-data.dtd	27025	2006-01-03
package-data	us-package-data.xml	19263	2006-01-03
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